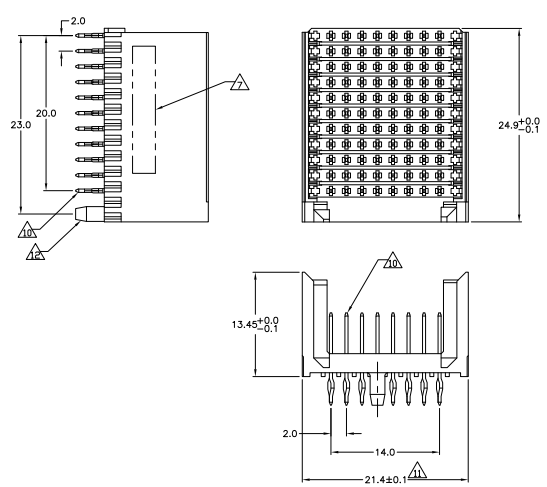


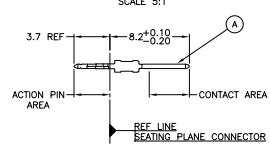
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REV	DATE	DESCRIPTION	BY	CHK
E1	18JAN2010	REV PER ECR-10-000662	JY	SY
F	10SEP10	ECR-10-018652	JS	MQW

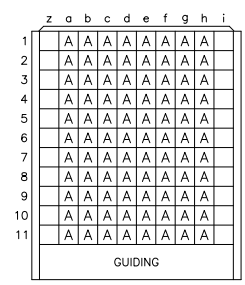
CONNECTOR ASSEMBLY EXEMPLARY LOADED



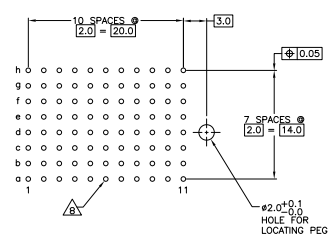
CONTACT DIMENSIONS



CONTACT LAYOUT



RECOMMENDED PCB-HOLE LAYOUT COMPONENT SIDE SHOWN



PLATED THRU HOLES PARAMETERS

REFERENCE APPLICATION SPECIFICATION

3-646457-0	
1-646457-9	
646457-9	
646457-4	
646457-1	
FINISH	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	13AUG10	BY	JY	CHK	SY
DESIGNED BY	J. SCHUPPER	DATE	10B-19082	REV	1	REV	F
DATE	114-19029	REV	1	REV	2	REV	F
CUSTOMER DRAWING	00779	0-646457					

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REV	DATE	DESCRIPTION	BY	APP
AD	00	SEE SHEET 1	-	-

- △ MATERIAL:
CONTACT: PHOSPHOR BRONZE.
HOUSING: GLASS-FILLED POLYESTER.
- △ GENERAL PLATING SPECIFICATION: UNDERPLATING
(ENTIRE CONTACT): 1.27µm MIN NICKEL AND ACTION
PIN: 0.5µm MIN TIN/LEAD.
FOR PLATING OF MATING SURFACES SEE APPLICABLE
SPECIFICATION REFERENCE FOR EACH DASH NUMBER.
- △ CONFORMS TO ALL TESTING ACCORDING TO IEC 61076-4-101
PERFORMANCE LEVEL 2.
- △ CONFORMS TO ALL TESTING ACCORDING TO IEC 61076-4-101
PERFORMANCE LEVEL 1.
- △ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL 3,
CENTRAL OFFICE APPLICATIONS.
- △ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL 3,
UNCONTROLLED ENVIRONMENT APPLICATIONS.
- △ CONNECTOR MARKED WITH PART NUMBER AND DATE CODE.
ADDITIONAL CHARACTERS OR MARKINGS, AS WELL AS THE LOCATION OF THE MARKINGS,
MAY BE ADDED FOR TRACEABILITY BASED UPON MANUFACTURERS DISCRETION.
- △ PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID
PATTERN DEFINED BY CONTACT LAYOUT.
- △ FOR ACTUAL PIN LOADING SEE "CONTACT LAYOUT".
- △ FOR ACTUAL PIN DIMENSIONS SEE "CONTACT DIMENSIONS".
- △ TO BE MEASURED AT BOTTOM OF SHROUD.
- △ LOCATION PEG.
- △ CONNECTOR LUBRICATED WITH BELCORE APPROVED LUBRICANT.
TECHNICAL REFERENCE: TR-NWT-001217 ISSUE 1, SEP 1992.
- △ 0.76µm MIN GOLD PLATING AT MATING SURFACES.

THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNED BY: S. MULLMAN	DATE: 11/08/02	Telcordia YTS Electronics Corporation Harrisburg, Pa 17105-3608	
DRAWN BY: J. SKIFFER		DATE: 11/08/02	MALE ASSEMBLY, 2-PACK 2mm HM, TYPE F		
CHECKED BY: J. SKIFFER		DATE: 11/08/02	DRAWN BY: J. SKIFFER		
APPROVED BY: J. SKIFFER		DATE: 11/08/02	DRAWN BY: J. SKIFFER		
DATE: 11/08/02		SIZE: A1		DATE: 11/08/02	DRAWN BY: J. SKIFFER
SEE SHEET 1		SEE SHEET 1		CUSTOMER DRAWING	